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Dr. Koichi Motoyama has been a Senior Engineer for advanced interconnect integration at IBM Research in Albany, New York since 2013. Currently, he is a lead integration engineer for developing post-Cu alternative metal interconnects in advanced nodes. Prior to joining IBM, he was employed at Renesas Electronics from 1998 until 2012 as a principal engineer and manager responsible for BEOL metallization development. He received IEEE IITC Michel Lerme Best Paper Award in 2018, 2020, and 2022. He has given invited talks and short course lectures in multiple conferences. He has reviewed papers for multiple journals and proceedings and has over 50 publications and 100 patents. He received his B.S. and M.S. in Chemistry from Keio University, and his Ph.D. in Materials Science from Tohoku University.